

IN THE CLAIMS:

Claims 2-13 have been amended herein. All of the pending claims 1 through 13 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Original) A lead frame for an integrated circuit package comprising: a composite lead frame of a plastic material having a portion thereof including an intrinsic conductive polymer.
2. (Currently Amended) The lead frame of claim 1, further comprising: an adhesive located on a portion of ~~said~~ the composite lead frame.
3. (Currently Amended) The lead frame of claim 1, wherein ~~said~~ the intrinsic conductive polymer is a polyaniline.
4. (Currently Amended) The lead frame of claim 1, wherein ~~said~~ the composite lead frame is transparent.
5. (Currently Amended) A circuit card comprising:
at least one electronic device;
a circuit card; and
at least one connector for attaching a portion of ~~said~~ the at least one electronic device to a portion of ~~said~~ the circuit card, ~~said~~ the at least one electronic device comprising an integrated circuit die attached to a portion of a plastic lead frame, ~~said~~ the plastic lead frame including an intrinsic conductive polymer.
6. (Currently Amended) The circuit card of claim 5, wherein ~~said~~ the plastic lead frame further comprises a plastic lead frame structure coated with a conductive polymer.

7. (Currently Amended) The circuit card of claim 6, wherein-said the conductive polymer coating is selected from the group consisting of polyaniline.

8. (Currently Amended) The circuit card of claim 7, wherein-said the polyaniline coating is of a thickness between about 25 μm and about 75 μm .

9. (Currently Amended) The circuit card of claim 5, wherein-said the plastic lead frame is composite plastic formed of a conventional polymer intermixed with a conductive polymer.

10. (Currently Amended) A computer system comprising at least one circuit card, said the at least one circuit card comprised of a plurality of electronic devices, at least one electronic device of said the plurality comprising at least one integrated circuit die connected to a portion of a plastic lead frame including an intrinsic polymer material.

11. (Currently Amended) The computer system of claim 10, wherein-said the plastic lead frame further comprises a plastic lead frame structure coated with a conductive polymeric coating.

12. (Currently Amended) The computer system of claim 11, wherein-said the conductive polymeric coating is selected from the group consisting of polyaniline.

13. (Currently Amended) The computer system of claim 10, wherein-said the plastic lead frame is composite plastic formed of a conventional polymer intermixed with a conductive polymer.